

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING SENT VIA FACSIMILE TO: COMMI  
FOR PATENTS, WASHINGTON, D.C. 20231, ON APRIL 17, 2002  
Depositor: ROSE MILLER

Rose Miller 4/17/02  
Signature And Date

#8/Response  
4/18/02  
BEST AVAILABLE COPY

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

April 17, 2002

Vincent J. McGahay, et al.

Examiner: Deven M. Collins

Serial No. 09/849,530

Group Art Unit: 2823

Filing Date May 7, 2001

Title: Method For Improving  
Adhesion To Copper

IBM Corporation - IPLaw Dept.  
Dept. 18G/Bldg. 300-482  
2070 Route 52  
Hopewell Junction, NY 12533

AMENDMENT

Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

FAX COPY RECEIVED

APR 17 2002

TECHNOLOGY CENTER 2800

Sir:

Responsive to the Office Action dated 02/14/02, Applicant respectfully request  
the Examiner to consider the following Remarks.